



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A1301-01** DATE: **January 29, 2013**
Product Affected: SSOP-40, SSOP-48, SSOP-80
(Refer to affected part list in Attachment 2)
Date Effective: **April 29, 2013**

MEANS OF DISTINGUISHING CHANGED DEVICES:
 Product Mark
 Back Mark Lot# will have a "Y" suffix
 Date Code
 Other

Contact: Mary Vesey
Title: Director, Product Assurance Attachment: Yes No
Phone #: (408) 284-4565
Fax #: (408) 284-1450 Samples: Samples available upon request
E-mail: Mary.Vesey@idt.com

DESCRIPTION AND PURPOSE OF CHANGE:

- | | |
|--|--|
| <input type="checkbox"/> Die Technology | This notification is to advise our customers that IDT plans to change from Gold bond wire to Copper bond wire for the selective products. This change is applicable to the existing qualified assembly sub-contractors of the affected part numbers. |
| <input type="checkbox"/> Wafer Fabrication Process | |
| <input type="checkbox"/> Assembly Process | |
| <input type="checkbox"/> Equipment | |
| <input checked="" type="checkbox"/> Material | There is no change in the moisture sensitivity performance. |
| <input type="checkbox"/> Testing | |
| <input type="checkbox"/> Manufacturing Site | Please refer to the following attachments for additional information. |
| <input type="checkbox"/> Data Sheet | Attachment 1 outlines the qualification results. |
| <input type="checkbox"/> Other | Attachment 2 shows the affected part numbers. |

RELIABILITY/QUALIFICATION SUMMARY:

There is no expected change to the product quality or reliability performance.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 90 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ *Approval for shipments prior to effective date.*
Name/Date: _____ E-Mail Address: _____
Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT 1 - PCN # : A1301-01

PCN Type: Assembly Material Change - Gold Wire to Copper Wire

Data Sheet Change: None

Details Of Change:

This notification is to advise our customers that IDT plans to change from Gold bond wire to Copper bond wire for the selective products. This change is applicable to the existing qualified assembly sub-contractors of the affected part numbers.

There is no change to the moisture performance of these packages.

Customers may expect to receive shipments with Copper wire process no sooner than 90 days from the date of this notification, January 29, 2013. Product assembled with Gold wire and Copper wire will be shipped during the transition period or until the Gold wire inventory has been depleted. However please note that product assembled with Gold wire and Copper wire will not be mixed in one tray stack, or tape and reel.

We request you to acknowledge receipt of this notification within 30 days of the date of this PCN notification. If you require samples to conduct an evaluation, please make your sample request within 30 days as samples are not built ahead of the change for all device options. You may contact your local sales representative to acknowledge this PCN and request samples.

Assembly Material : There is no change in the mold compound and die attach materials. The material sets used in assembly is in compliance with RoHS 6 (green products) requirement. There is no change in the moisture sensitivity performance.

Sample Availability : Samples are not built ahead of the change for all device types and may not be available for all affected device types.
Please contact your local IDT sales representative for your sample request and availability.



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ATTACHMENT 1 - PCN # : A1301-01

Qualification Test Result :

Qual Vehicle: SSOP-80 (1 lot)

Test Description	Test Method	Test Results (SS / Rej)
* High Accelerated Stress Test (Biased, 130 °C/85% RH, 100 Hrs)	JESD22-A110	30/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	30/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	30/0
Bond Shear	JESD22-B116	5/0

Note:

* Test requires moisture pre-conditioning sequence per JESD22-A113C and will use the existing moisture sensitivity level that has been qualified for this material set.

2. Product Electrical Characterization

Product electrical characterization has been successfully completed on representative product families and copper wire performance was comparable to gold wire performance.



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ATTACHMENT 2 - PCN #: A1301-01

Affected Part Numbers

IDT Part Number	IDT Part Number	IDT Part Number	IDT Part Number
QS32X2245Q2G	QS32X861Q1G	QS32XVH384Q1G	QS34XVH2245Q3G
QS32X2245Q2G8	QS32X861Q1G8	QS32XVH384Q1G8	QS34XVH2245Q3G8
QS32X2384Q1G	QS32XL384Q1G	QS34X2245Q3G	QS34XVH245Q3G
QS32X2384Q1G8	QS32XL384Q1G8	QS34X2245Q3G8	QS34XVH245Q3G8
QS32X245Q2G	QS32XVH2245Q2G	QS34X245Q3G	QS4A215Q1G
QS32X245Q2G8	QS32XVH2245Q2G8	QS34X245Q3G8	QS4A215Q1G8
QS32X384Q1G	QS32XVH245Q2G	QS34X383Q3G	
QS32X384Q1G8	QS32XVH245Q2G8	QS34X383Q3G8	